



City, Docket No. CPAC 1002-1  
App. No. 09/802,375

PATENT

#10/a  
11/25/02  
Schmidt

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Nazir AHMAD, *et al.*

Application No.: 09/802,375

Filed: March 9, 2001

Title: **Packaging structure and method**

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) Examiner: Quang D. VU

)  
) Group Art Unit: 2811

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) Date: November 13, 2002

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) CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on November 13, 2002.

Signed

*Linda Shaw*

Linda Shaw

COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

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AMENDMENT

Dear Sir:

Responsive to the Office Action mailed May 13, 2002, kindly amend the application as follows.

In the Claims

Please amend claims 1 and 14 as shown on the attached "Attachment under Rule 1.121", as follows.

1. (Amended) A method for providing connection between a flip chip and a substrate, comprising

providing a chip having a set of bumps formed on a bump side thereof;

providing a substrate having a set of interconnect points on a metallization thereon;

providing a measured quantity of a polymer adhesive in a middle region of the chip on the bump side;

aligning the chip with the substrate so that the set of bumps aligns with the set of interconnect points;

pressing the chip and the substrate toward one another so that a portion of the polymer adhesive contacts the substrate and the bumps contact the interconnect points; and